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(54) Title: SYSTEMS AND METHODS FOR PURIFYING SOLVENTS

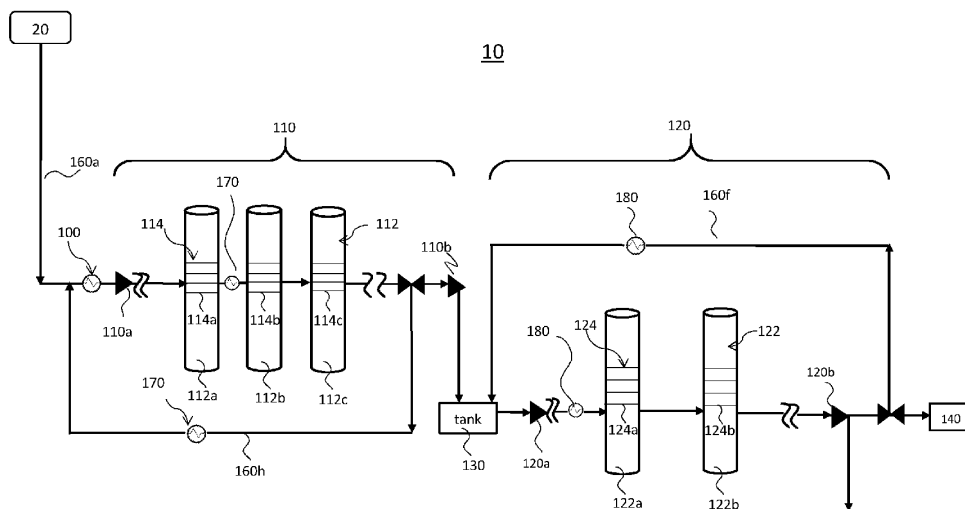


Figure 1

(57) Abstract: The present disclosure is directed to methods of purifying solvents. The purified solvents can be used for cleaning a semiconductor substrate in a multistep semiconductor manufacturing process.

[Continued on next page]

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